## Welcome

9:15 – 9:45 Introducing DESY and the CMS group Introduction (Guenter) Test beam activities for the pixel (Hanno) Simulation studies for phase II (Thomas)

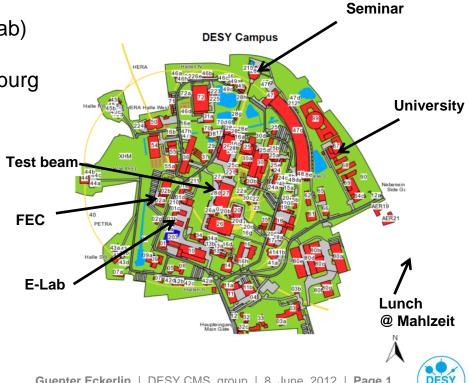
9:45 – 10:30 visiting the E-Lab and the test beam area

10:30 – 11:15 visit to FEC (electronics lab)

11:30 – 12:30 visit to University of Hamburg

12:30 - 14:00 lunch

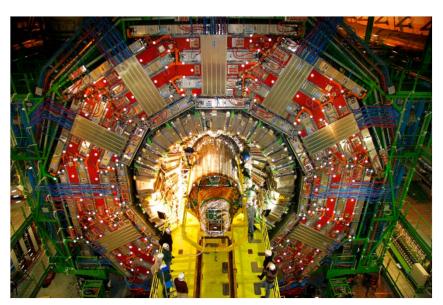
15:00 joint instrumentation seminar





# CMS @ DESY

## The CMS group at DESY



- DESY in a nutshell
- The CMS group at DESY
- Program for today

Günter Eckerlin Introduction to visitors June, 2012







## **DESY** in a nutshell

DESY is a research center of the Helmholtz Association

HELMHOLTZ ASSOCIATION

Established on 18 December 1959 in Hamburg

Locations: Hamburg and Zeuthen/Brandenburg (near Berlin)





Annual budget: 192 MEuro

90% funded by the German Federal Ministry of Education and Research, 10% funded by the city of Hamburg and the Federal State of Brandenburg

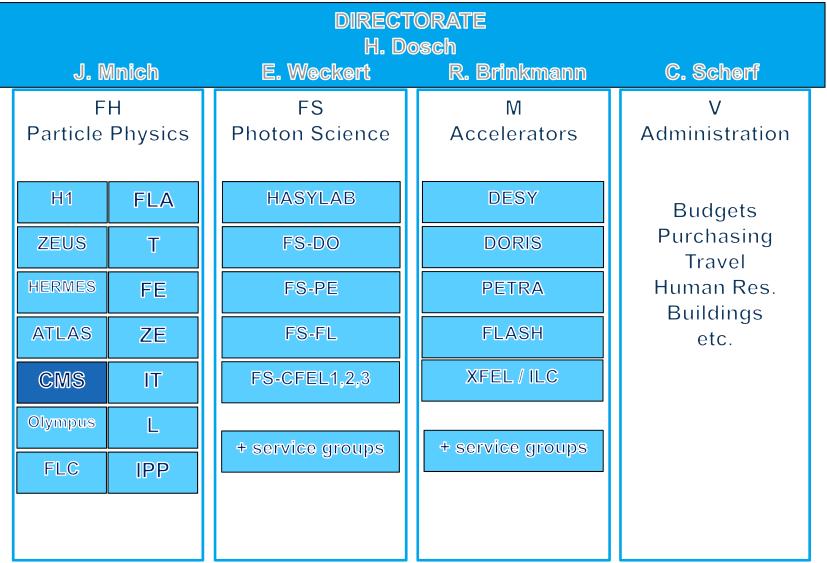
2000 employees including 650 scientists 3000 guest scientists More then 700 postdocs and students (doctoral and non-doctoral)

Working on
Accelerator science
Photon science
Particle and Astroparticle physics





# **DESY organizational structure**







# The CMS group

DESY is member of the CMS Collaboration since 2006

Current status (June 2012):

- ~ 80 Members (6 in Zeuthen)
- ~ 50 FTE
  - 17 perm. staff
  - 18 students (doctoral and non-doctoral)
  - 1 engineer, 3 technicians (2xmech, 1xelectr.)

53 CMS authors (3rd biggest Institute of CMS)

Available infrastructure

DESY central workshops

ZM central mechanics service group

ZE central electronics service group

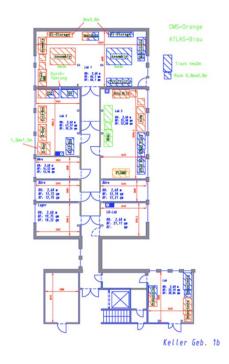
FH specific

FE (electronic engineering group) (visit of FEC)

Electronic Lab (~ 200m² lab space + ~30m² 'clean room')

FH-Mechanics workshop (~200m²)

Close cooperation with Univ. Hamburg







# The CMS group – organizational structure

Head of the Group - K.Borras; Deputy - G.Eckerlin

Physics - A.Meyer

Top

Higgs

SUSY

QCD

**PDF** 

M.Aldaya A.Meyer A.

Raspereza Pe

I.Melzer-Pellmann H.Jung Th.S.-S. K.Borras K.Lipka

Components and Operation

DQM

A.Meyer

Tracker

G.Eckerlin

Alignment

R.Mankel

Computing

M.Kasemann

**BCM** 

W.Lohmann

CASTOR HLT/DAQ K.Borras

Upgrade - G.Eckerlin

Workshop and technical staff K.Borras G.Eckerlin I.Gregor (ATLAS) Pixel

D.Pitzl G.Eckerlin Tracker

G.Eckerlin W.Lohmann HCAL

K.Borras I.M.-P. **BCM** 

W.Lohmann A.Raspereza





# **DESY tracker upgrade activities**

### Phase I - pixel barrel layer 4

Daniel Pitzl, Doris Eckstein, Hanno Perrey, Alexey Petrukhin, Shiraz Habib, Armin Burgmeier Luigi Caligaris, Thomas Eichhorn, Jan Hampe (FEC)

Setup of module production center (in cooperation with Univ. of Hamburg)
Module test and cold calibration
Test beam and source (presentation by Hanno Perrey)
x-ray calibration (see visit to University of Hamburg)

b-tagging simulation studies for HLT (pixel only) (Maria Aldaya, Jan Olzem)

#### Phase II - tracker

Andreas Mussgiller, Doris Eckstein, Hanno Perrey, Thomas Eichhorn, Zeuthen: Wolfgang Lohmann, Wolfgang Lange, Matthias Bergholz

DESY is member of the CEC (HL-LHC tracker R&D)

### HPK campaign

diode campaign coordination (Doris Eckstein) sensor(diode) characterization (see visit to University of Hamburg) sensor simulation (presentation by Thomas Eichhorn)

### Modules & new materials

FEA, deformation setup, new materials, ...(Andreas Mussgiller)





# **Program for today**

9:15 – 9:45 Introducing DESY and the CMS group Introduction (Guenter) almost done! Test beam activities for the pixel (Hanno) Simulation studies for phase II (Thomas)

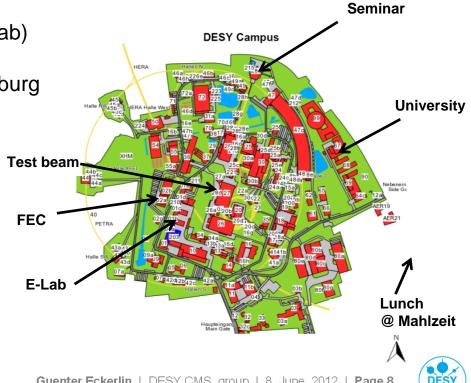
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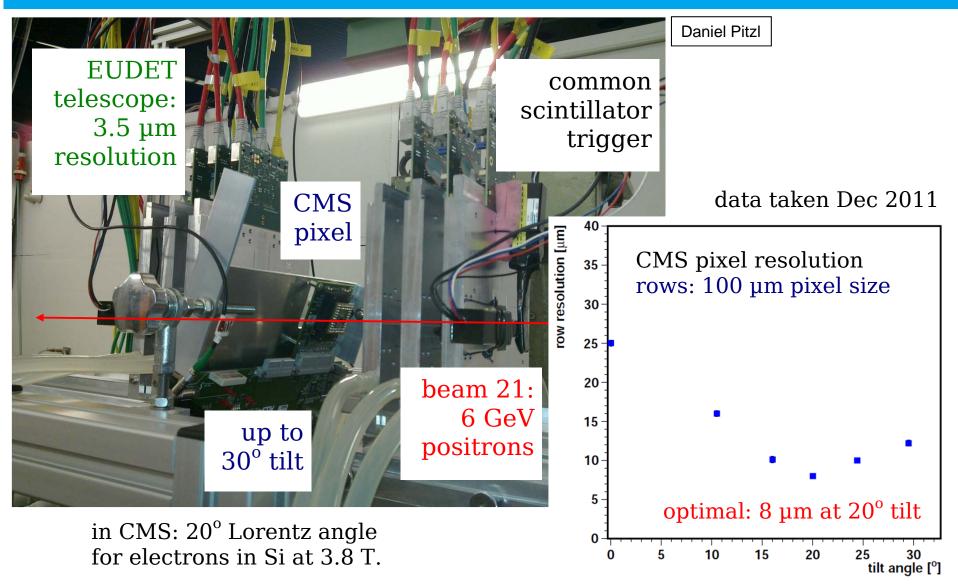


# **Backup slides**





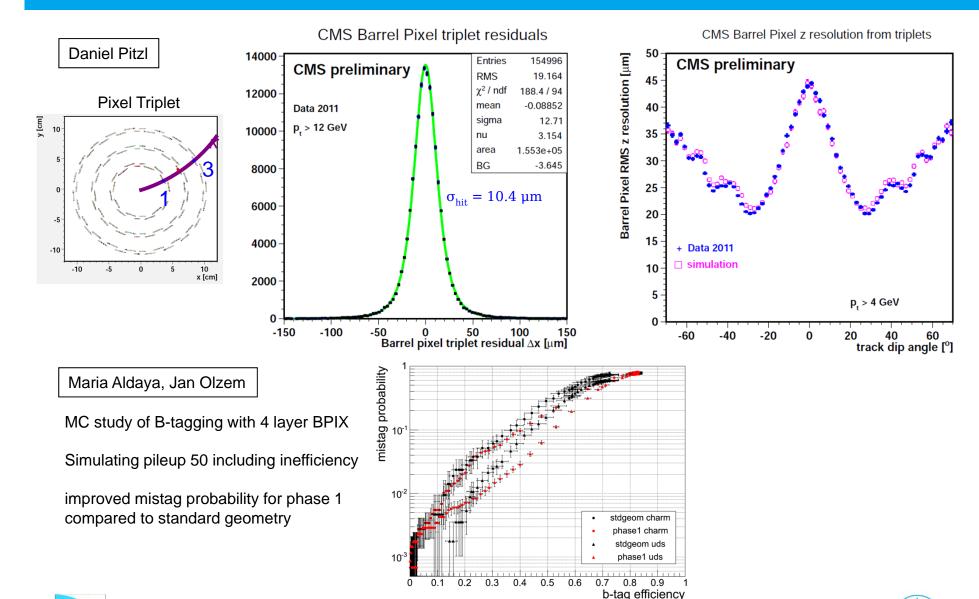
# **Testing CMS Pixel in the DESY test beam**







# Example of DESY activities for pixel upgrade in 2011







# Pixel Bump Bonding Tests (example Pac Tech)

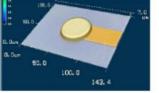
## Solder bumps were placed and reflowed successfully

Jan Hampe

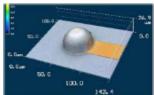
PLANNED PROCESS AND LASER SCAN AND OPTICAL MICROSCOPE PICTURES

Planned and tested Solder Ball Jetting process





Pad with processed UBM



Pad bumped with 40 µm solder ball



Side view of bumbed daisy chain structure on chip









DESY-CMS BPIX production Bumping and FC bond tests

2012/01/17



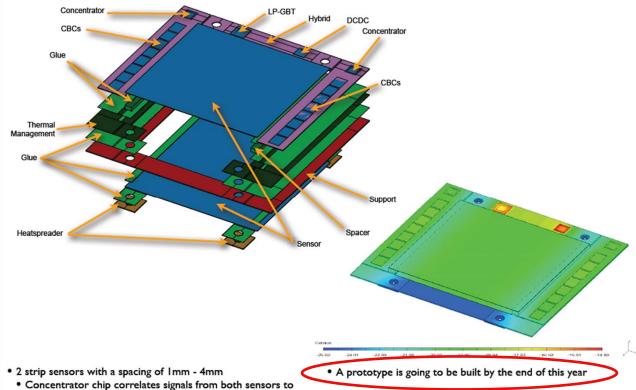


## Phase II – Tracker Module R&D

Andreas Mussgiller, Jan Olzem

Detailed FEA simulation of modules thermal and mechanical essential input for module design thermal and deformation tests in preparation to validate results ODM ready by end of Aug. 2012 will help to characterize materials will be used to test prototypes plan to build and test prototypes at DESY in cooperation with FEC

### Design and FEA of the 2S Module





form a Pt trigger

• Trigger will be used in LI





**Doris Eckstein** 

### **Involvements in Phase 2 upgrade:**

### **CEC (HPK Campaign):**

- diode sensor programme coordination (Doris)
  - have to finish irradiations and measurements this year 2012 to be able to contribute to sensor material choice
- · device simulation (Thomas) starting now
  - Embedded in sensor WG, coordinated by Alberto Messineo

# Setup of clean room with Probe station + ALIBAVA setup + TCT setup:

test of any strip sensors in the Lab with Laser and source (Doris +?)

### **Eudet/AIDA Telescope:**

- · Gaining experience in using Eudet Telescope at DESY Testbeam (Thomas, Hanno)
- Close collaboration with ATLAS colleagues
- → Will enable us to test strip sensors with ALIBAVA readout and in future also CMS readout here at DESY

### **Involvement in Phase 1:**

- Testbeams with Eudet telescope and pixel module (Hanno, Thomas)
- Soon setup of clean room with Probestation etc. (Doris +?)







